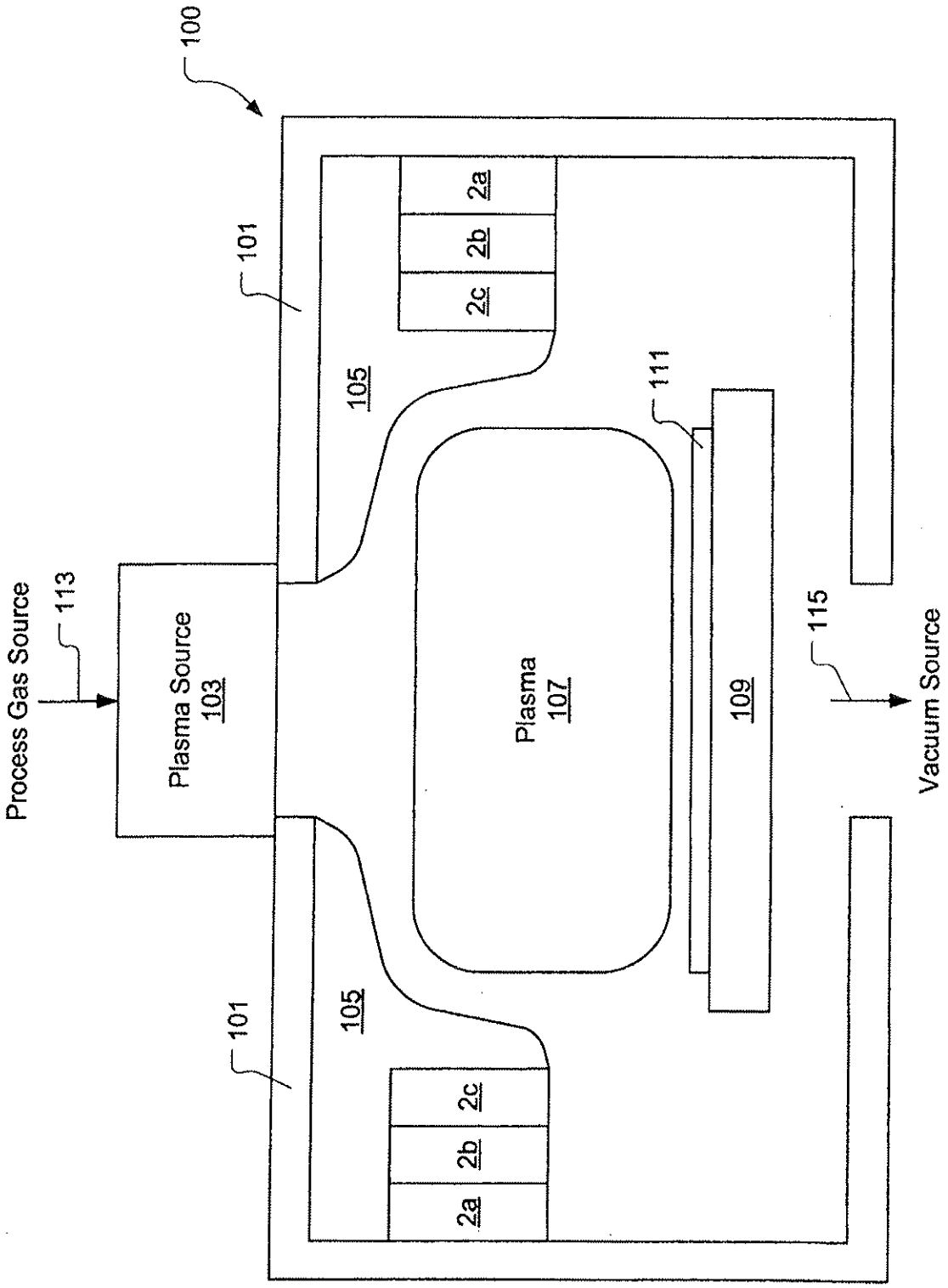

100
101
2a
2b
2c
105
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
2c
2b
2a

Fig. 1A

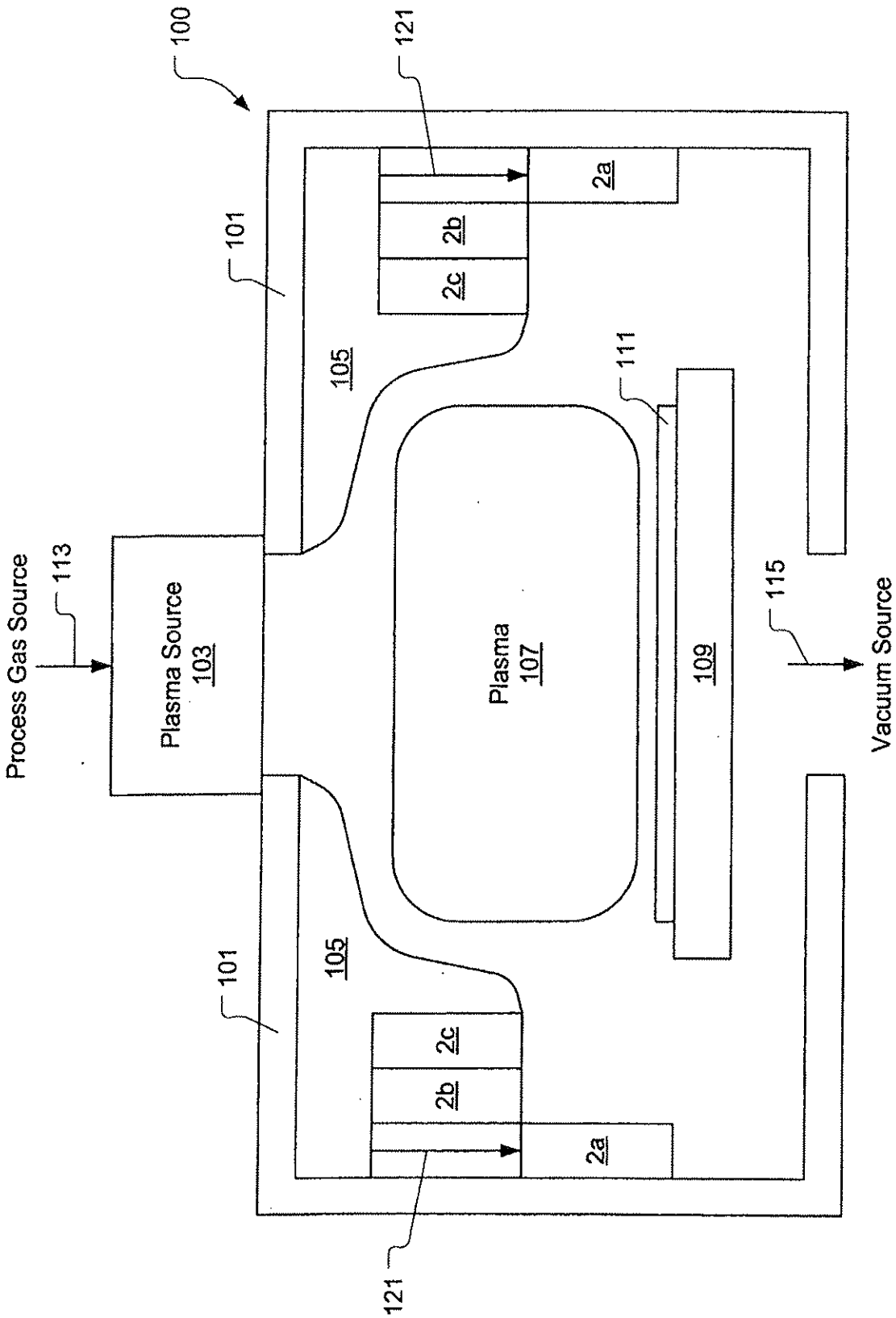

100
121
101
2a
2b
2c
105
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
2c
2b
2a
121

Fig. 1B

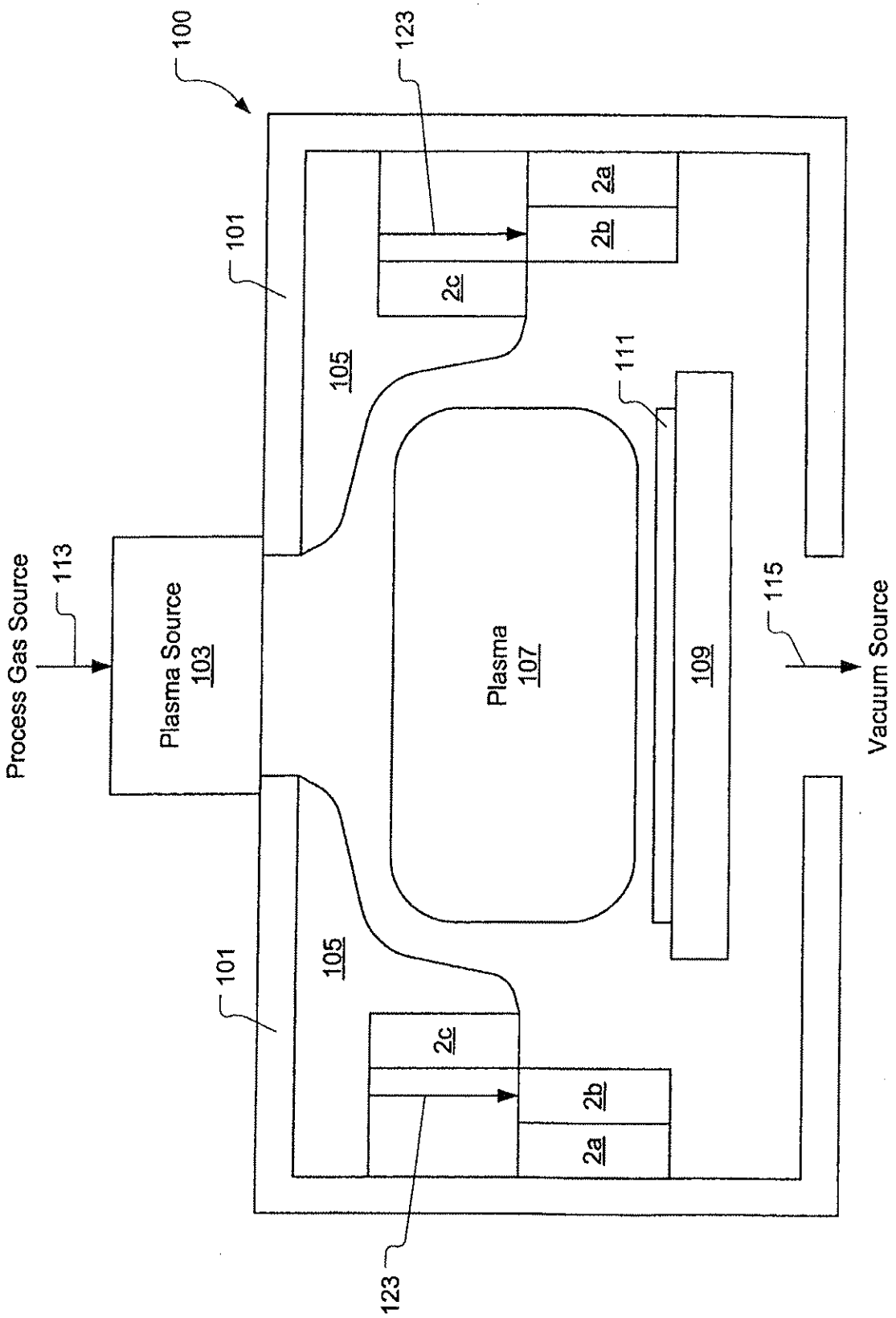

100
123
101
2a
2b
2c
105
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
2c
2b
2a
123

Fig. 1C

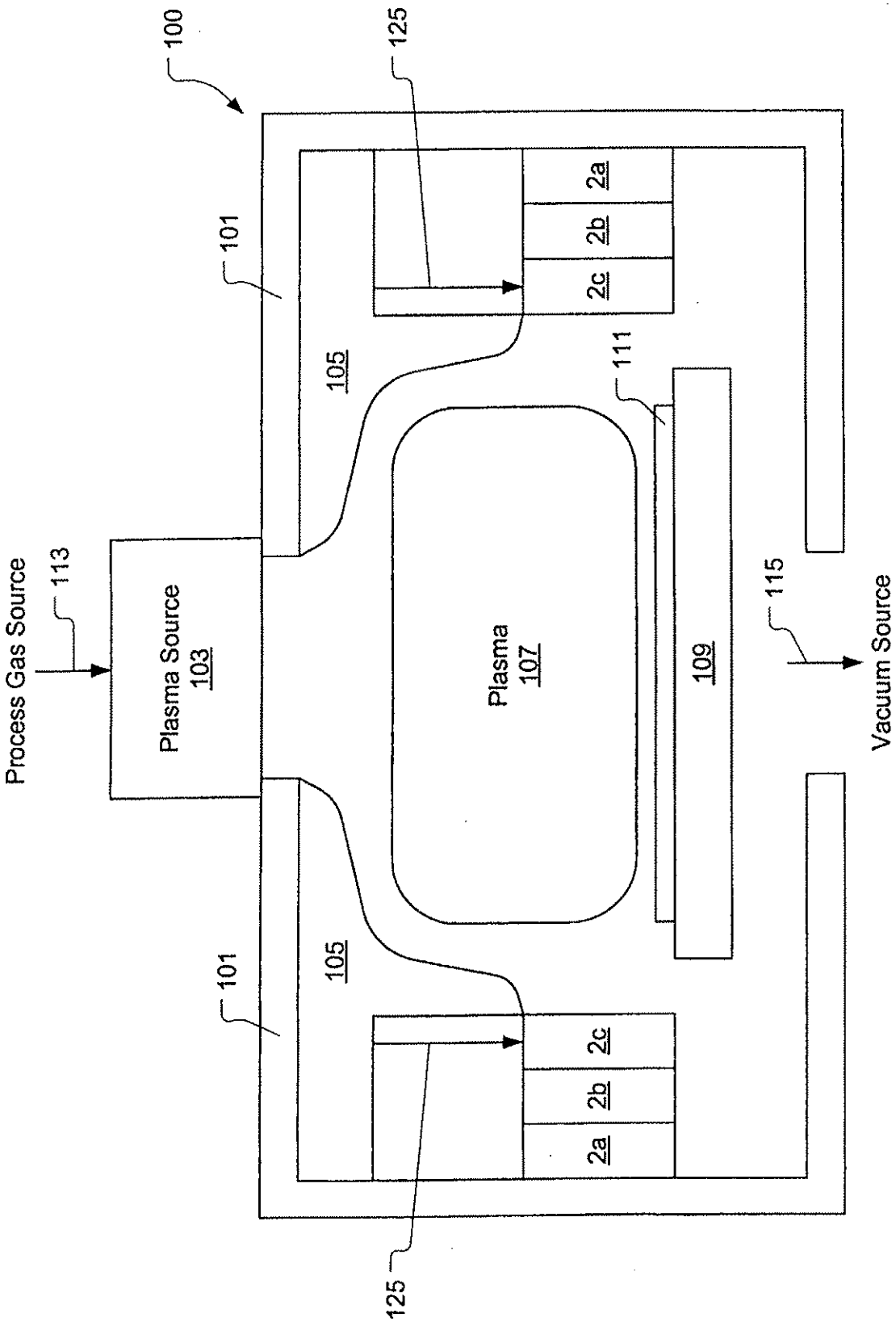

100
125
101
105
2a
2b
2c
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
2c
2b
2a
125

Fig. 1D

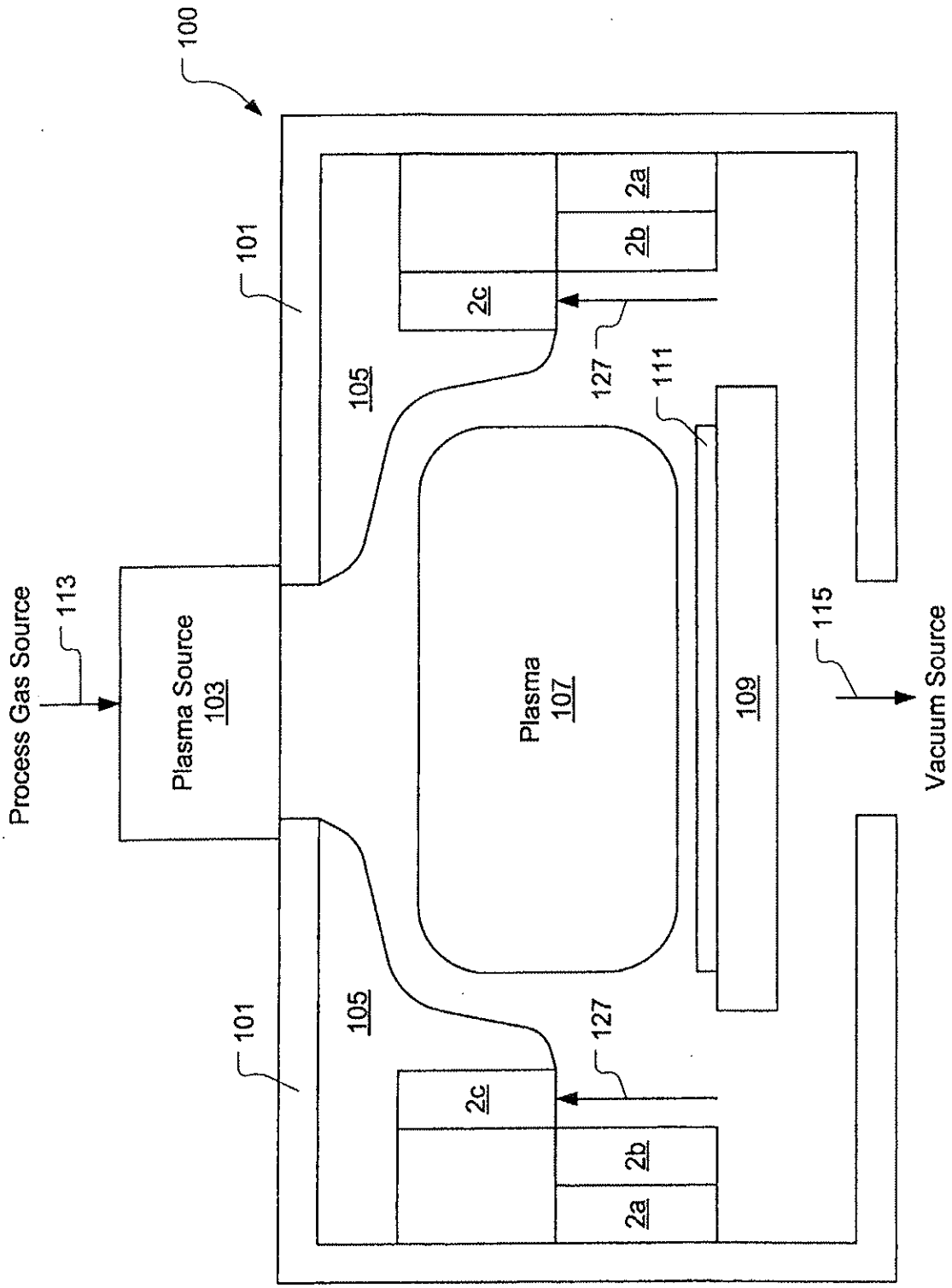

100
101
105
2a
2b
2c
127
111
109
Plasma
107
Plasma Source
103
Process Gas Source
113
115
Vacuum Source

Fig. 1E

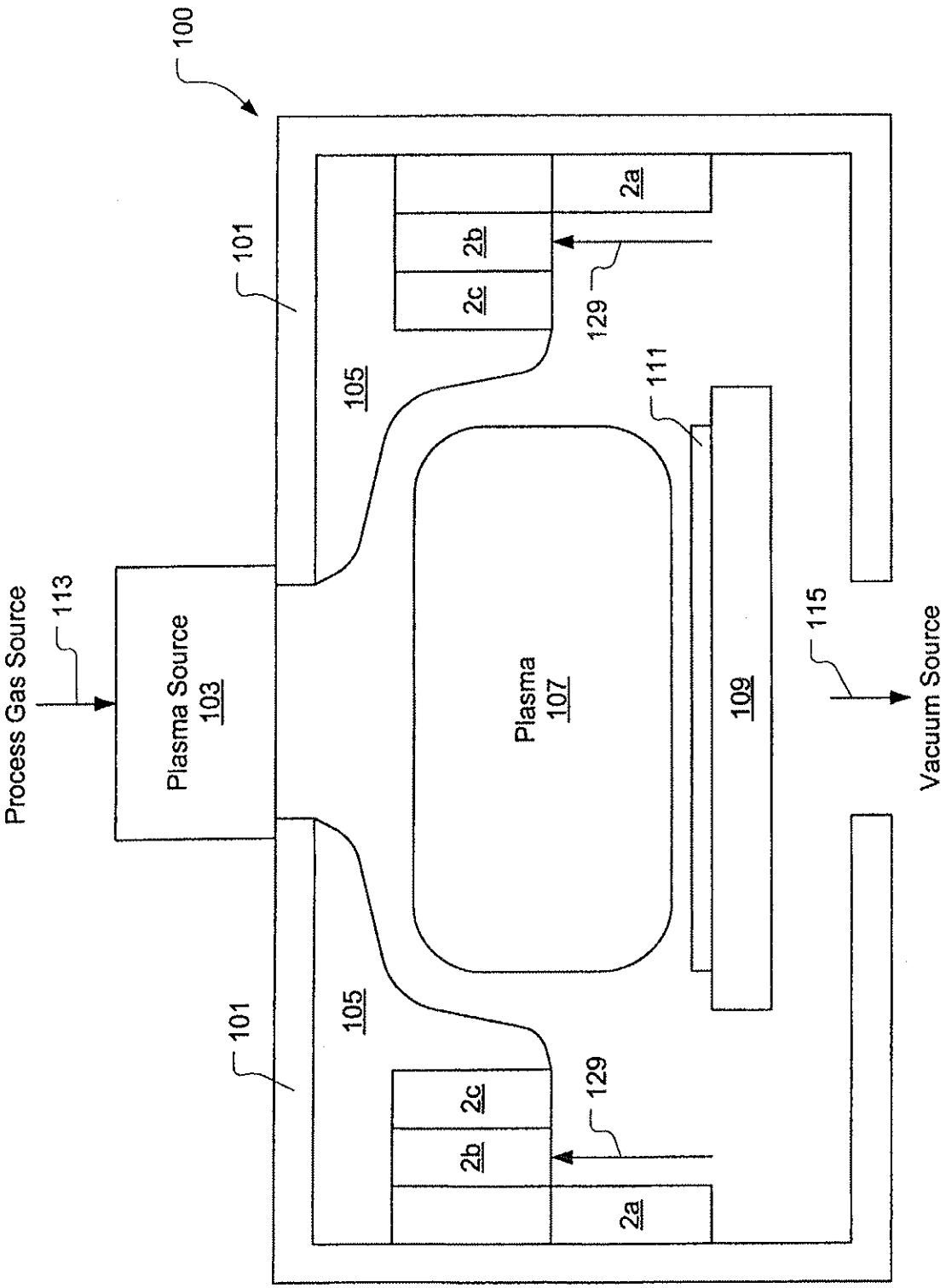

100
101
101
105
105
2a
2b
2c
2c
2b
2a
129
129
111
109
Plasma
107
Plasma Source
103
Process Gas Source
113
115
Vacuum Source

Fig. 1F

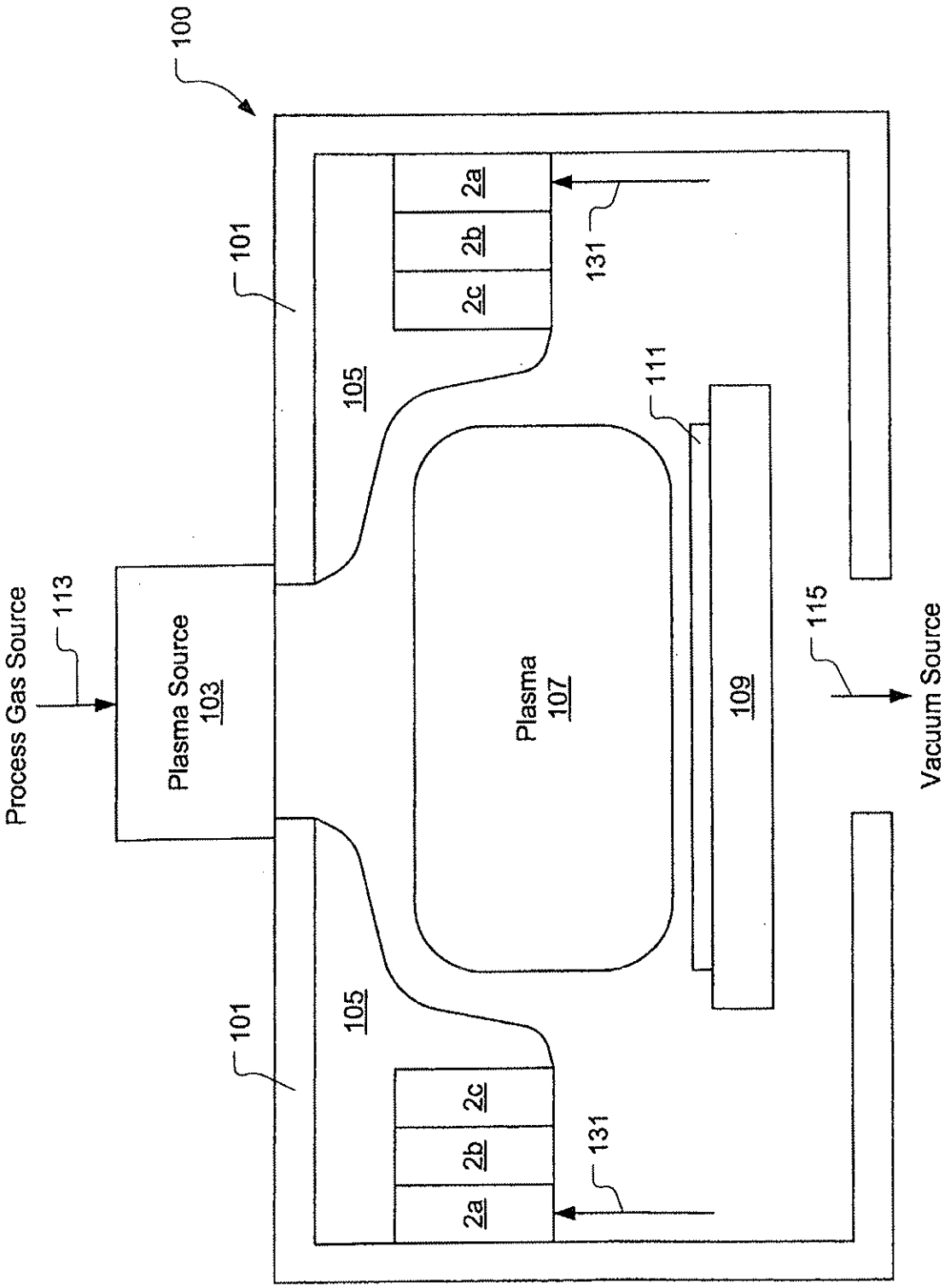

100
101
101
105
105
2a
2b
2c
2a
2b
2c
131
131
111
109
Plasma
107
Plasma Source
103
Process Gas Source
113
115
Vacuum Source

Fig. 1G

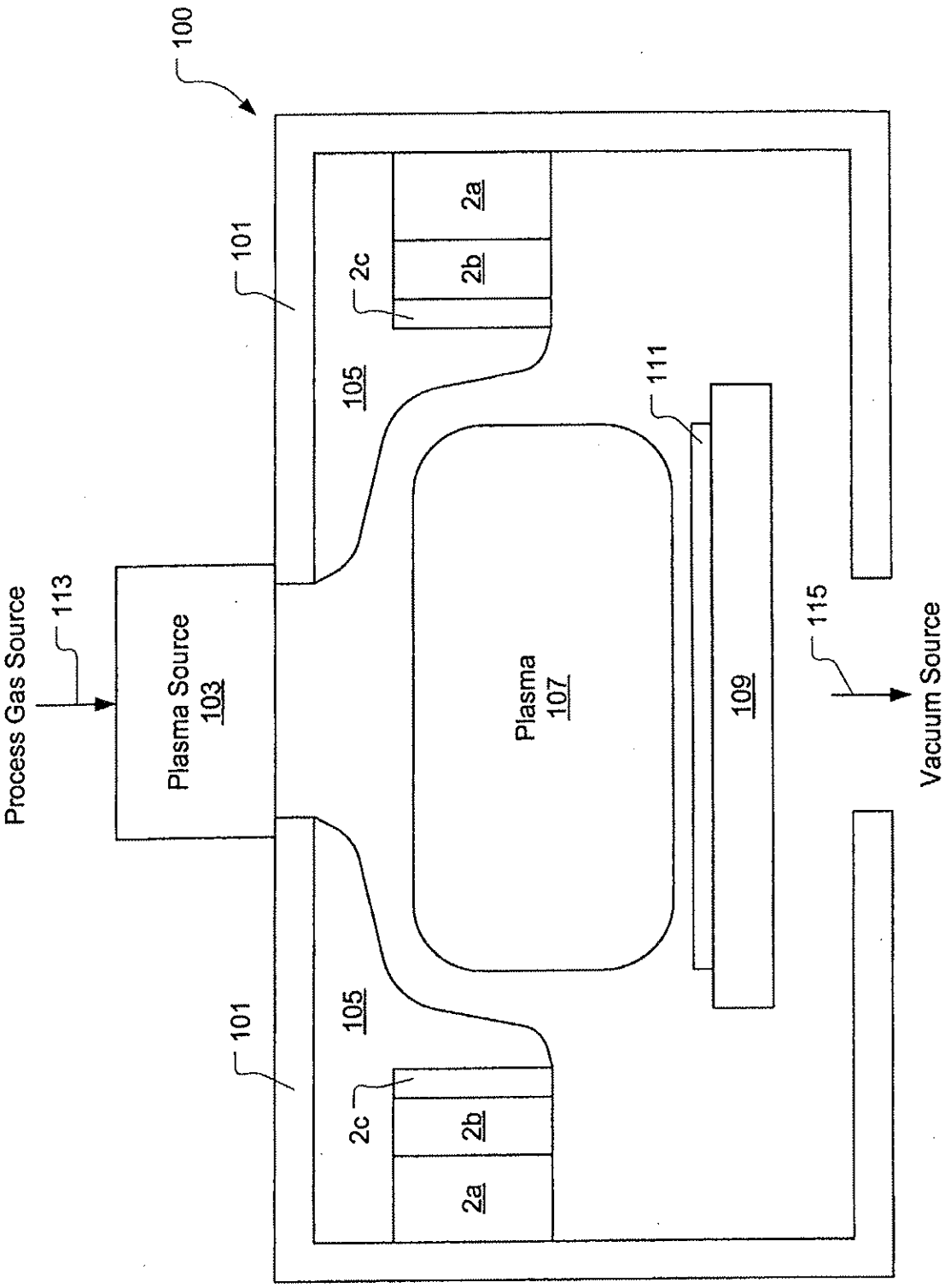

100
101
2a
2b
2c
105
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
2c
2b
2a

Fig. 2

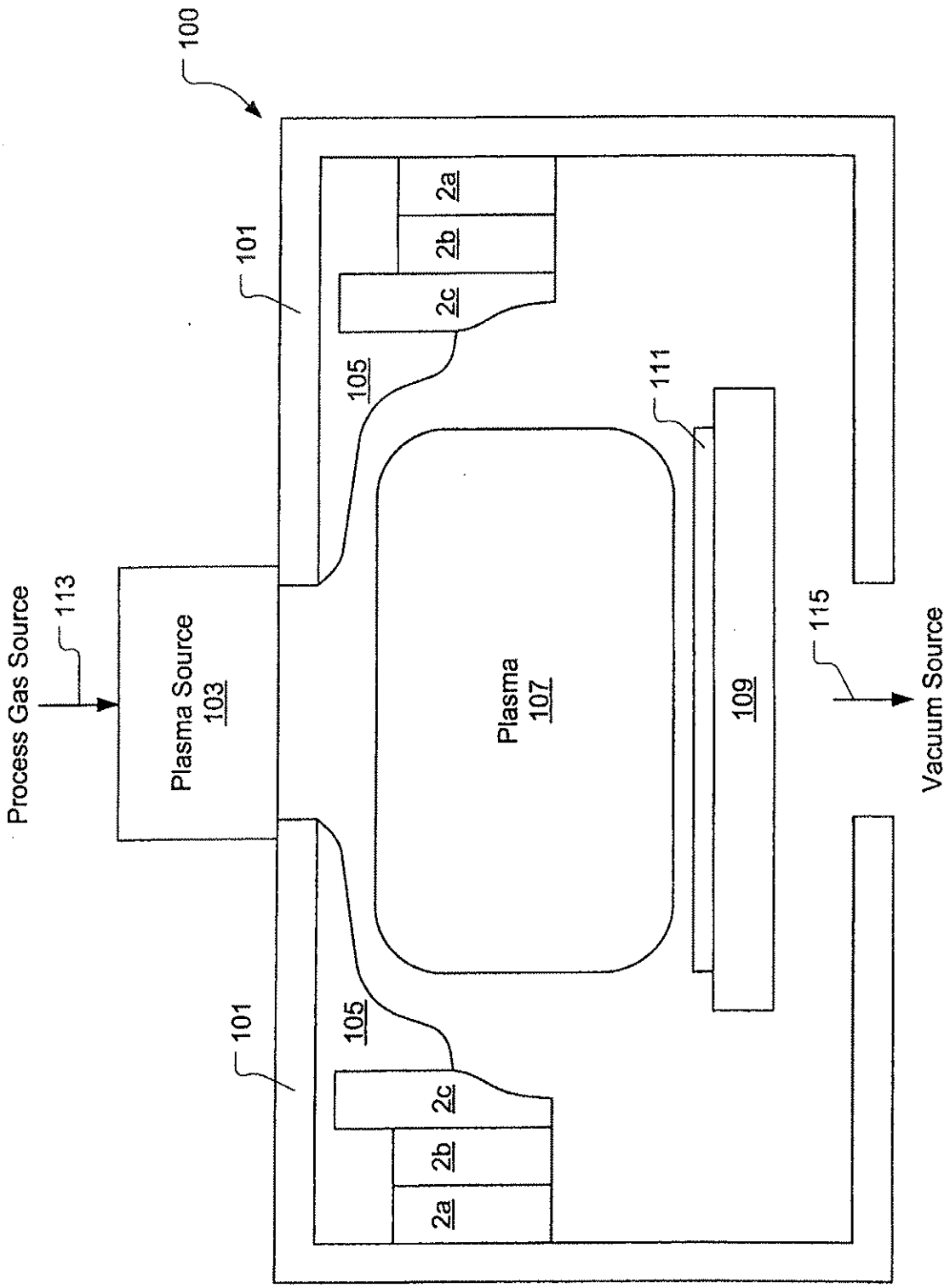

100
101
2a
2b
2c
105
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
2c
2b
2a

Fig. 3

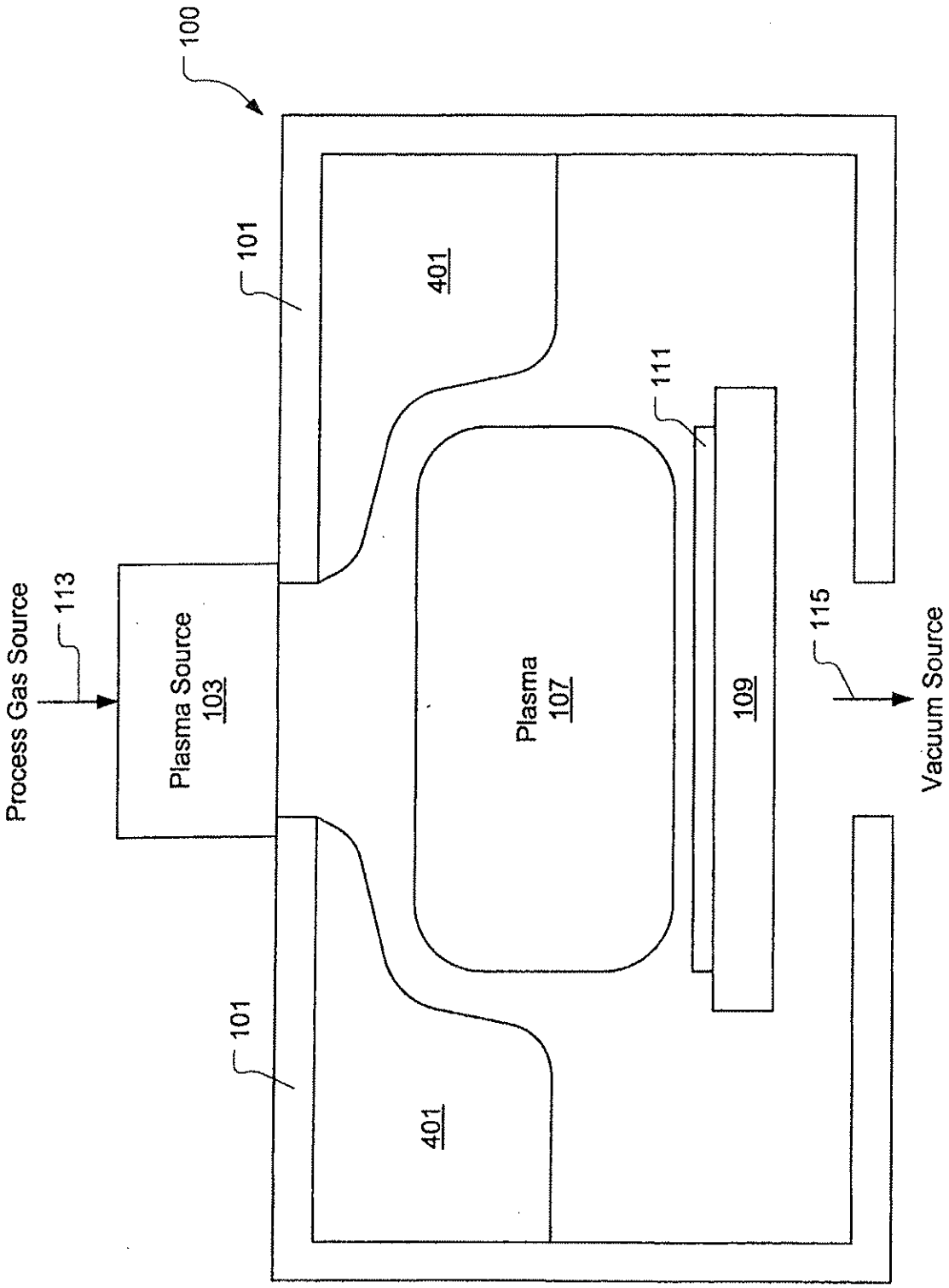

100
101
401
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
401

Fig. 4A

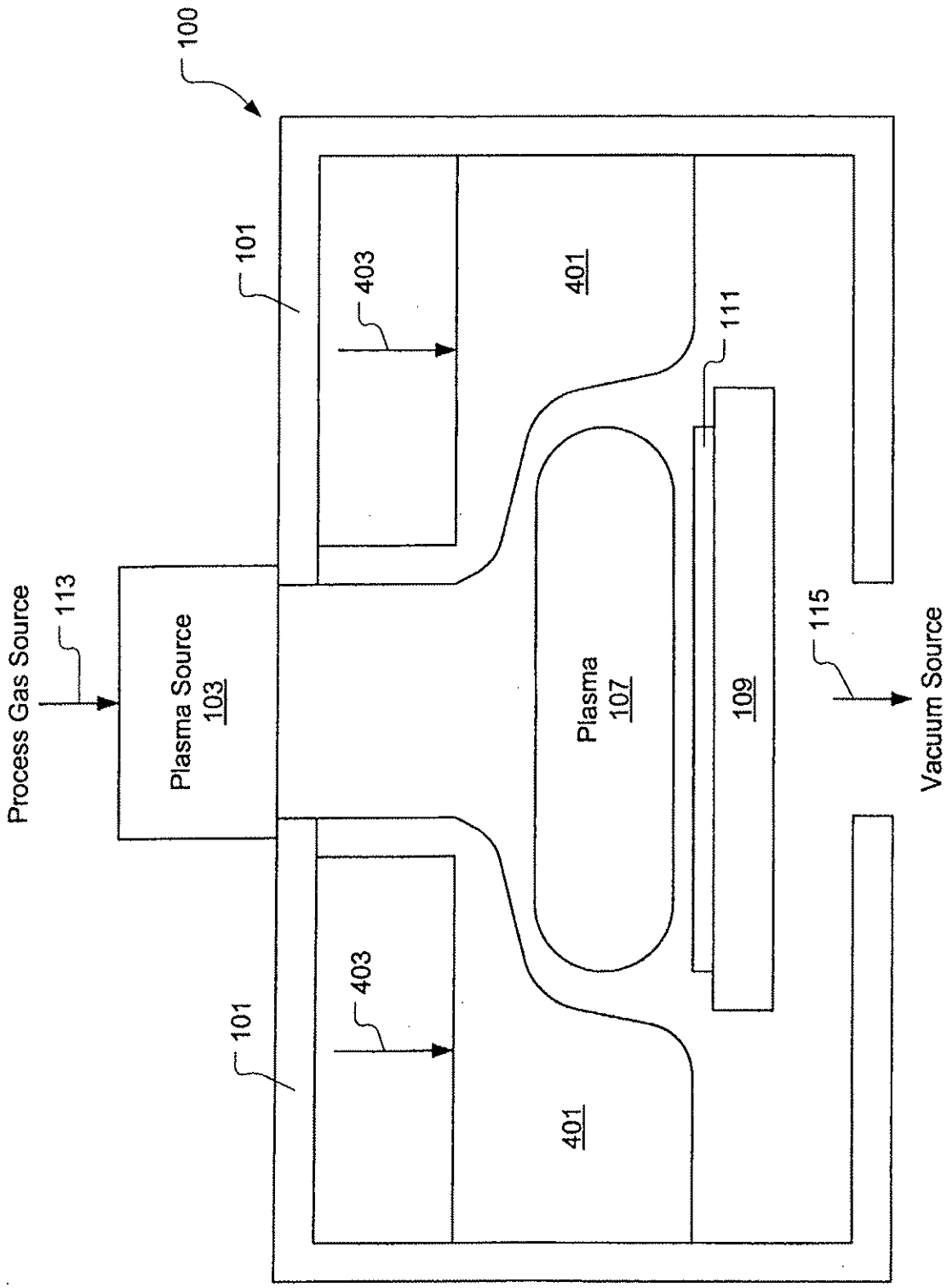

100
101
403
401
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
403
401

Fig. 4B

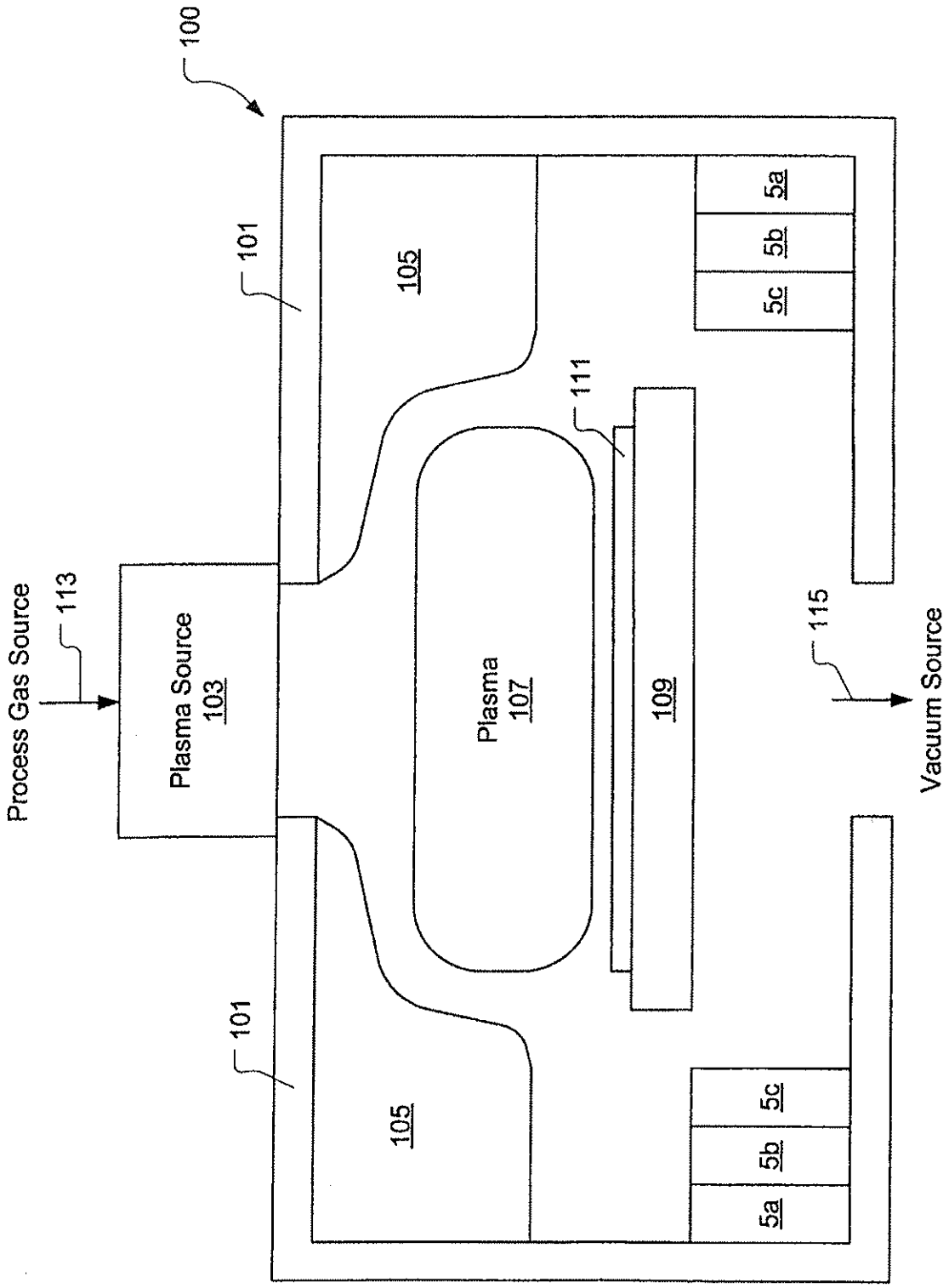

100
101
105
5a
5b
5c
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
5c
5b
5a

Fig. 5A

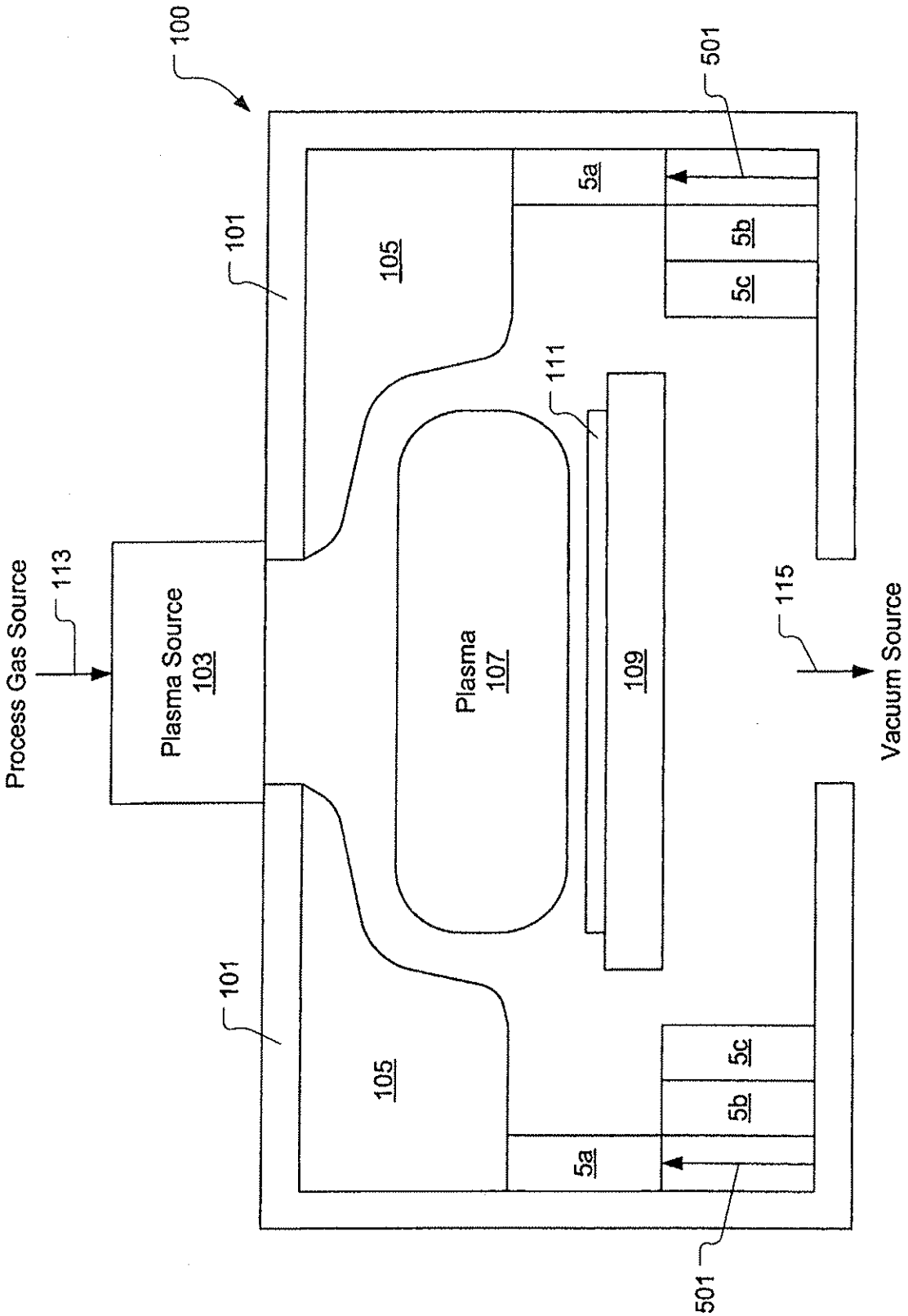

100
501
101
105
5a
5b
5c
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
5c
5b
5a
501

Fig. 5B

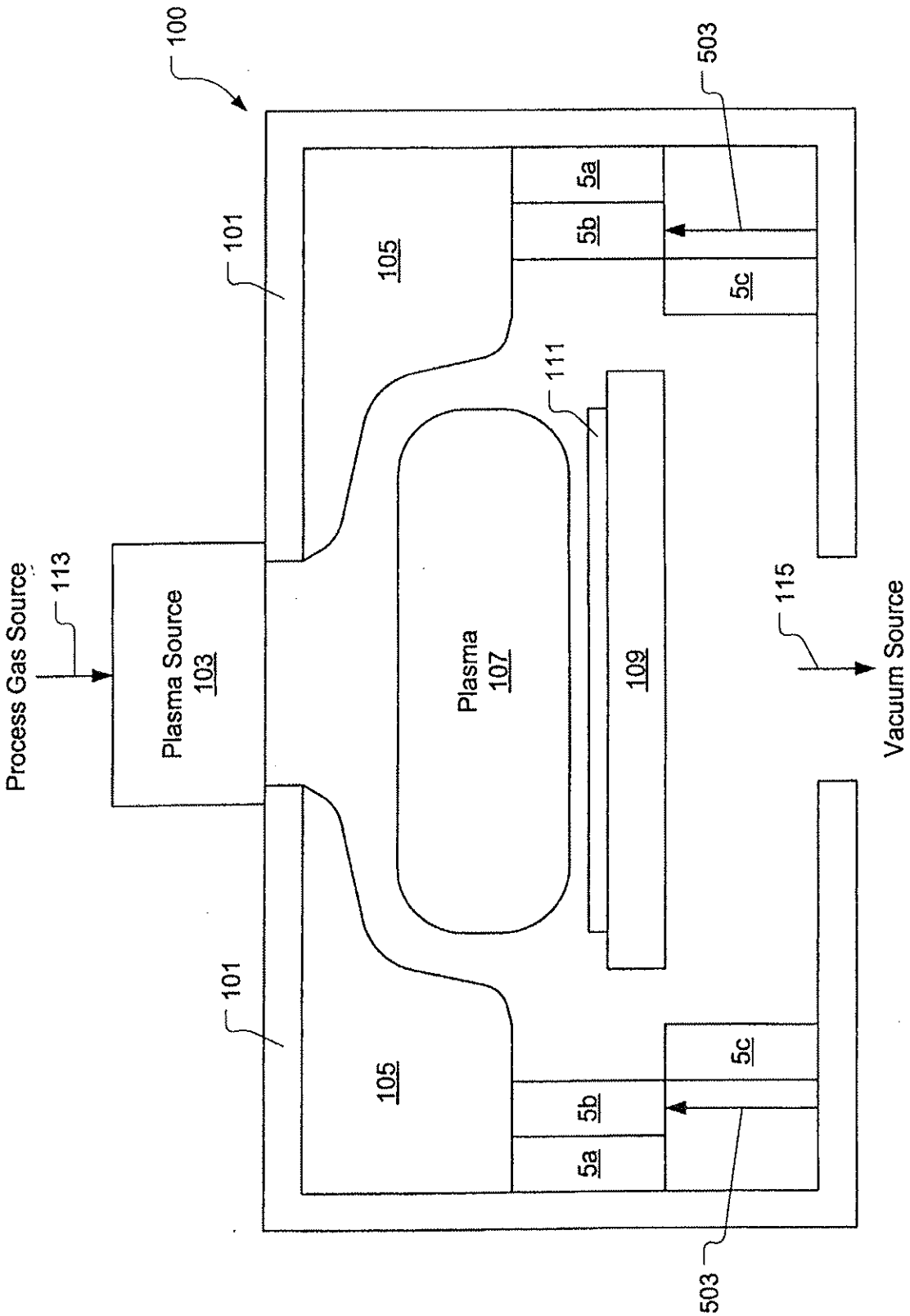

100
503
101
105
5a
5b
5c
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
5c
5b
5a
503

Fig. 5C

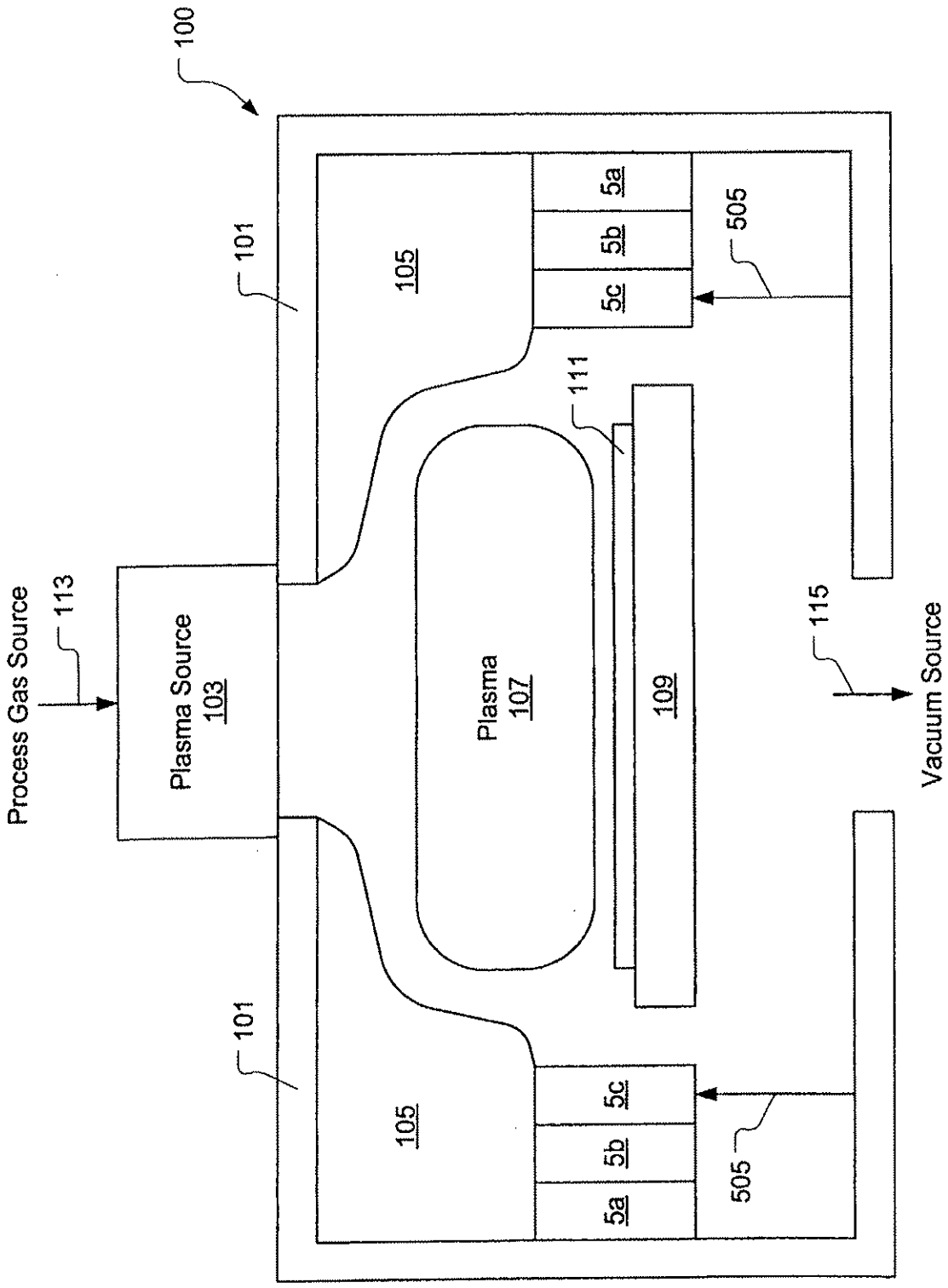

100
101
105
5a
5b
5c
505
111
Plasma Source
103
Plasma
107
109
Process Gas Source
113
115
Vacuum Source
101
105
5c
5b
5a
505

Fig. 5D

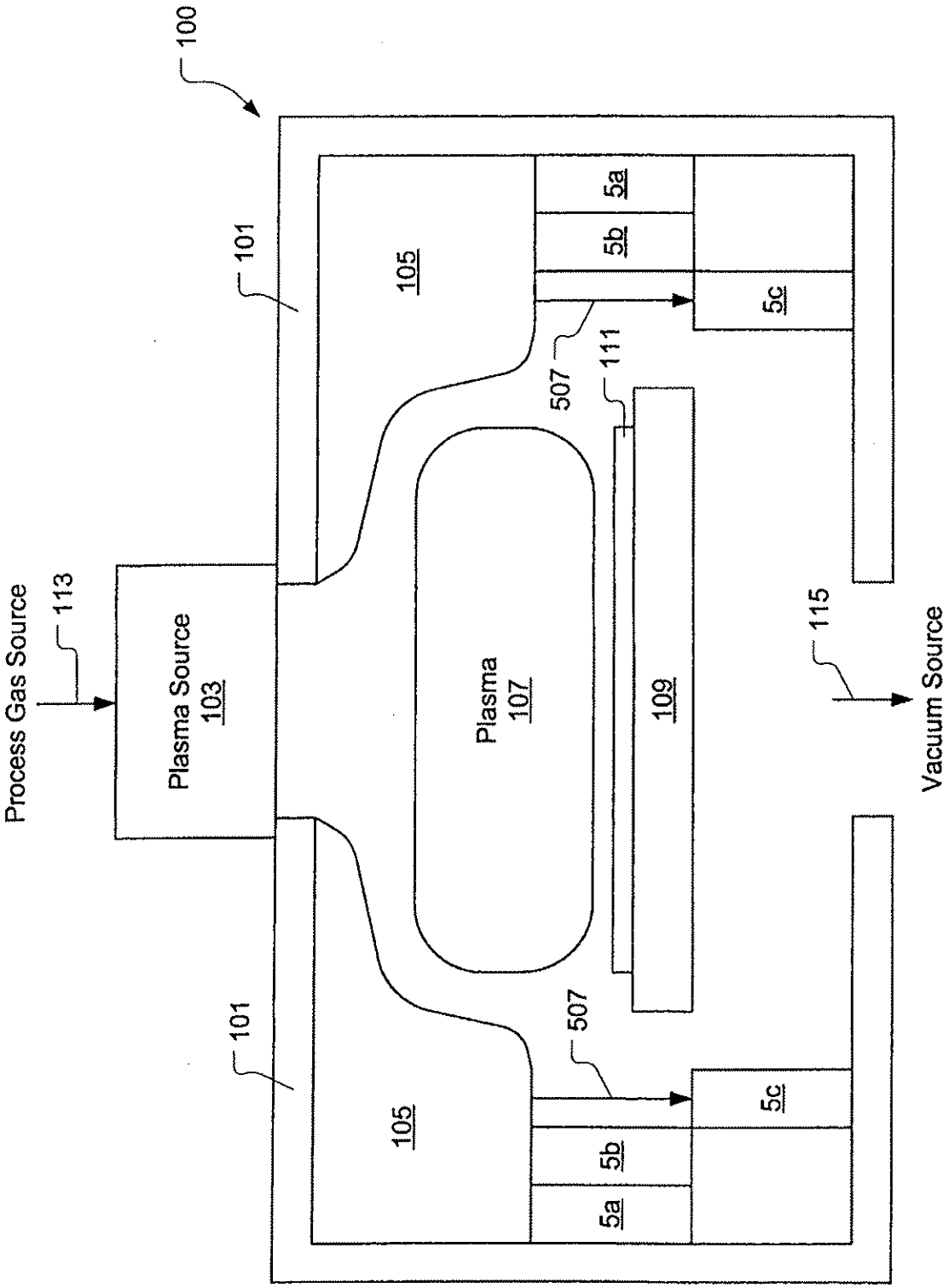

100
101
105
5a
5b
5c
507
111
Process Gas Source
113
Plasma Source
103
Plasma
107
109
115
Vacuum Source
101
105
507
5c
5b
5a

Fig. 5E

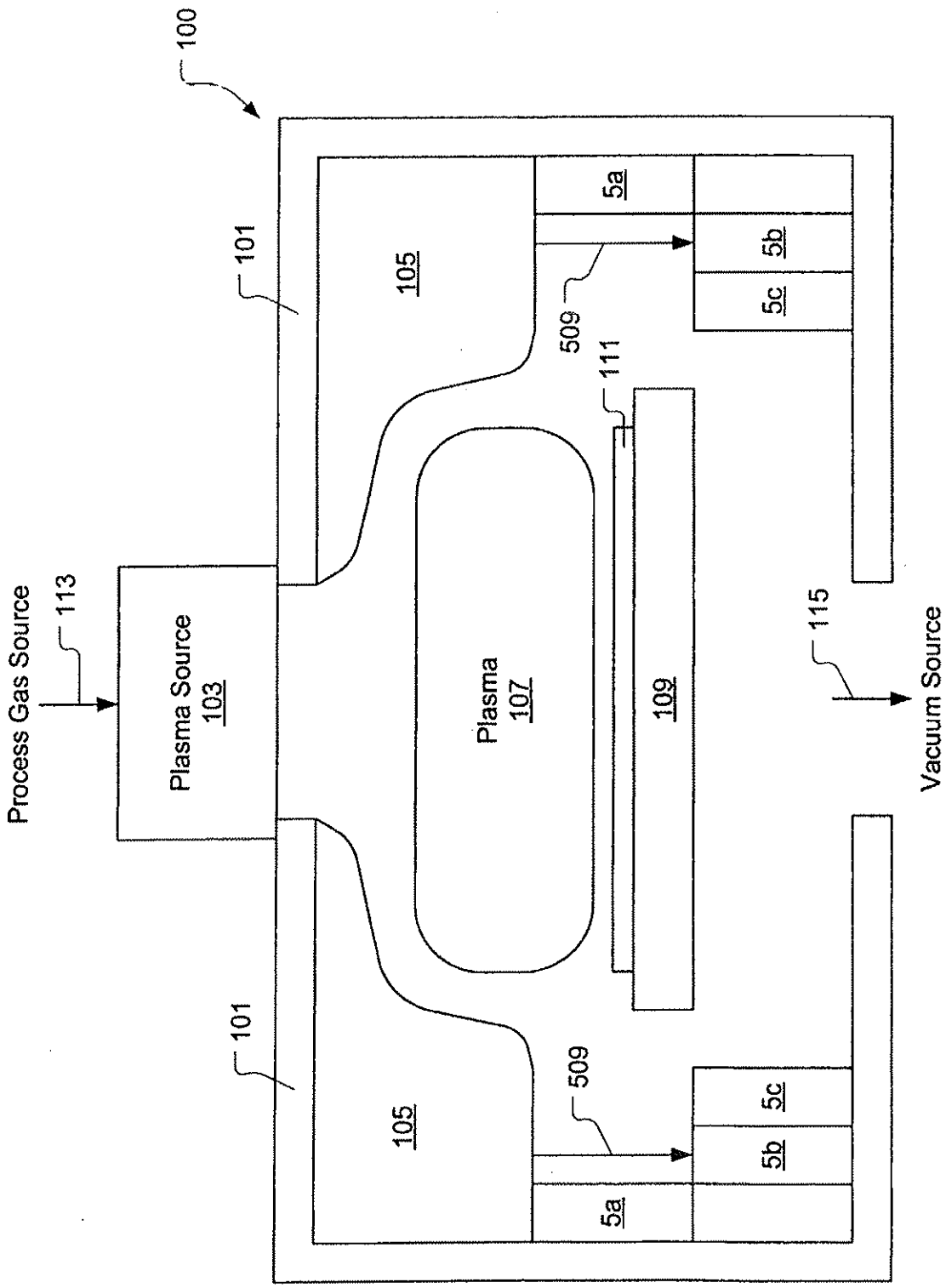

100
101
105
5a
5b
5c
509
111
Plasma Source
103
Process Gas Source
113
Plasma
107
109
115
Vacuum Source
101
105
509
5c
5b
5a

Fig. 5F

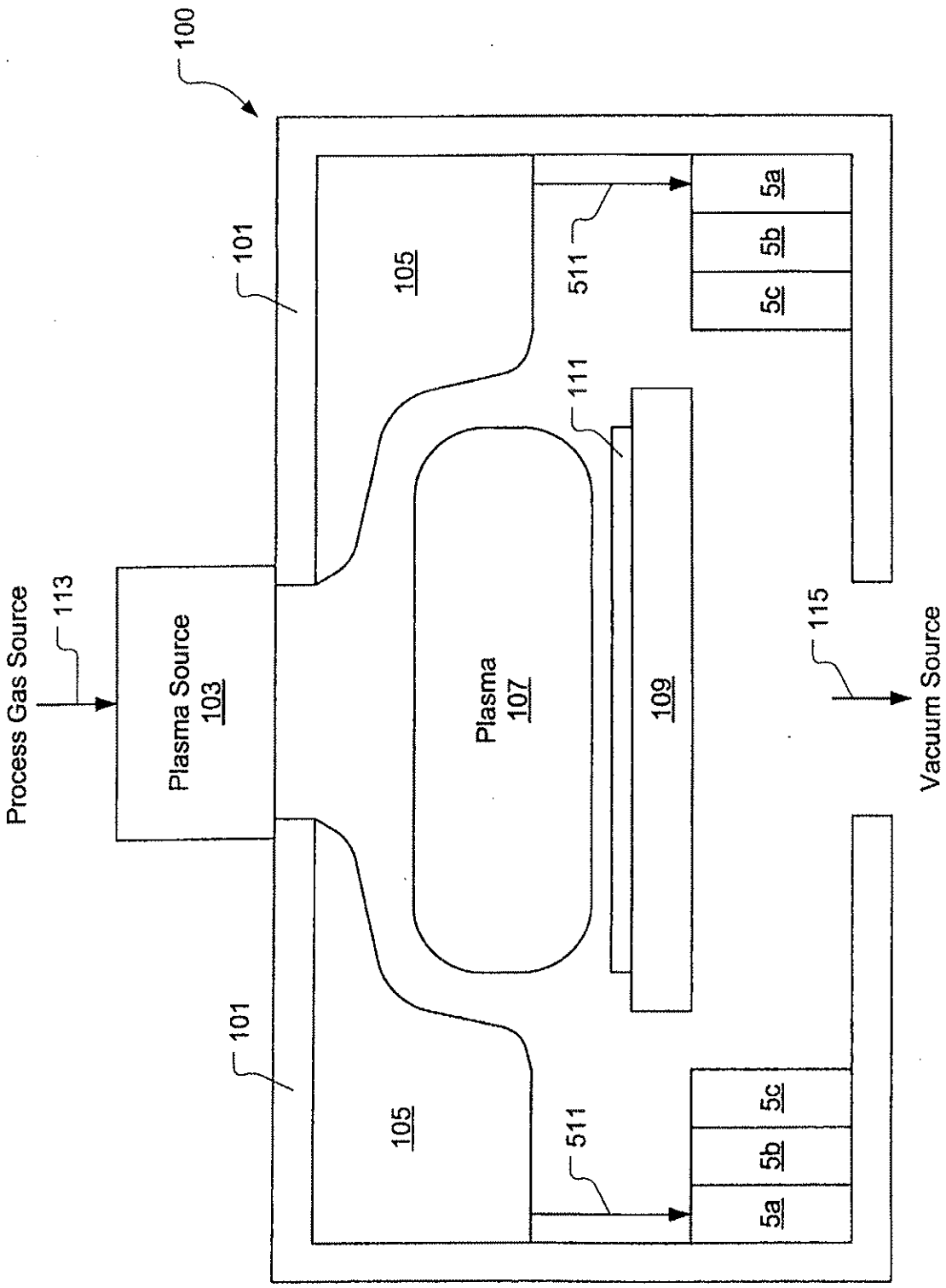

100
101
105
511
5a
5b
5c
111
Plasma Source
103
Plasma
107
109
Process Gas Source
113
115
Vacuum Source
101
105
511
5c
5b
5a

Fig. 5G

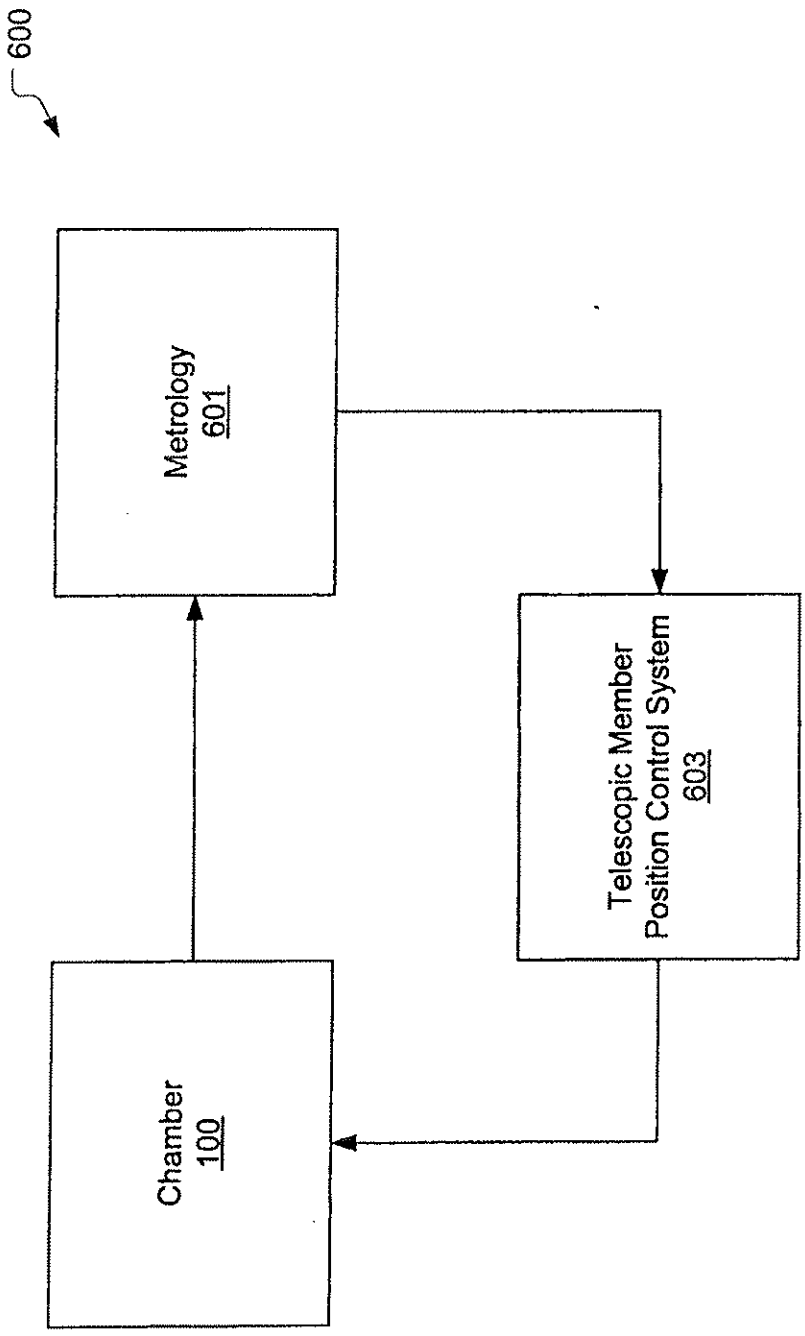

600
Metrology
601
Telescopic Member
Position Control System
603
Chamber
100

Fig. 6

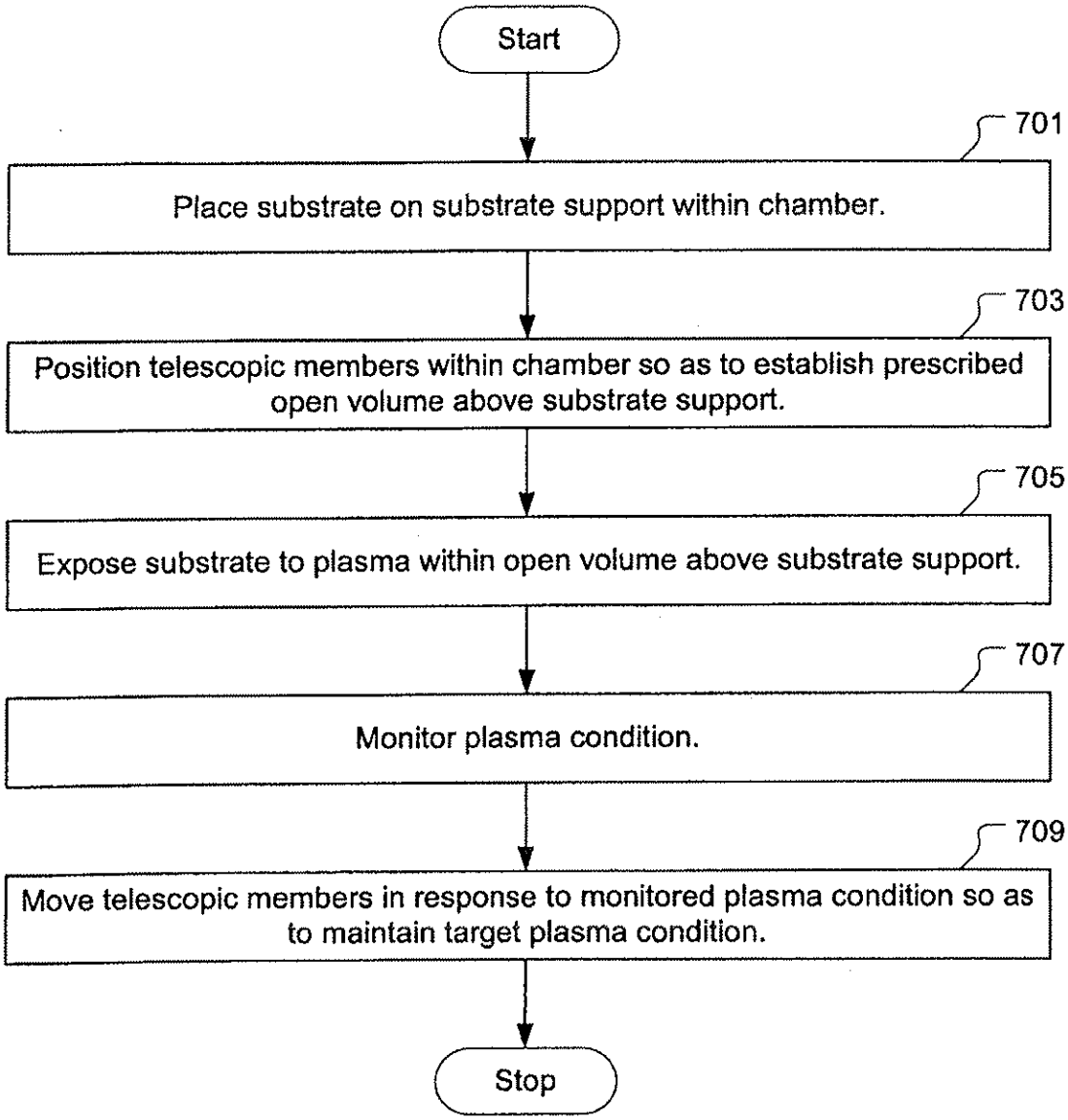

Start
701
Place substrate on substrate support within chamber.
703
Position telescopic members within chamber so as to establish prescribed open volume above substrate support.
705
Expose substrate to plasma within open volume above substrate support.
707
Monitor plasma condition.
709
Move telescopic members in response to monitored plasma condition so as to maintain target plasma condition.
Stop

Fig. 7